



ALLIANCE MEMORY MDS REPORT

| Part Number: | | | | AS9F38G08SA-25BIN | | | | | | | |
|--------------|----------------------------|-----------|------------------------------|--|--|--------------|------------|----------------------------|-------------|----------------|-------------|
| Part Weight: | | | | 142.00035mg | | | | | | | |
| Item | Material | | | Substance | | | Weight(mg) | Homogeneous Material Level | | Product Level | |
| | Type | Vendor | Model | Name | Purpose | CAS No. | | Percentage (%) | PPM (mg/kg) | Percentage (%) | PPM (mg/kg) |
| 1 | Silicon Chip | - | 4G Nand x8 4b | Silicon (Si) | Circuit | 7440-21-3 | 24.53647 | 99.596% | 995,960 | 17.27916% | 172,792 |
| | | | | Oxygen | | 7782-44-7 | 0.00049 | 0.002% | 20 | 0.00035% | 3 |
| | | | | Boron | | 7440-42-8 | 0.09904 | 0.402% | 4,020 | 0.06974% | 697 |
| 2 | Substrate | LIST | SU-FBJS-06303W H Rev.0 | Glass cloth | CCL | 65997-17-3 | 6.76309 | 18.00% | 180,000 | 4.76273% | 47,627 |
| | | | | Resistant Epoxy Resin | CCL | 223769-10-6 | 2.25436 | 6.00% | 60,000 | 1.58758% | 15,876 |
| | | | | Heat Resistant Resin | CCL | 25722-66-1 | 1.12718 | 3.00% | 30,000 | 0.79379% | 7,938 |
| | | | | Silica Filler | CCL | 7631-86-9 | 3.75727 | 10.00% | 100,000 | 2.64596% | 26,460 |
| | | | | BOEHMTE | CCL | 1318-23-6 | 0.75145 | 2.00% | 20,000 | 0.52919% | 5,292 |
| | | | | Copper | CCL | 7440-50-8 | 22.91935 | 61.00% | 610,000 | 16.14035% | 161,403 |
| | | | | | | | | 100.00% | 1,000,000 | | |
| | | | | 2-Benzyl-2-(dimethylamino)-4'-morpholinobutyrophenone | PSR-4000 | 119313-12-1 | 0.08460 | 2.50% | 25,000 | 0.05957% | 596 |
| | | | | Propanol,1(or 2)-(2-methoxymethylethoxy)- | PSR-4000 | 34590-94-8 | 0.15227 | 4.50% | 45,000 | 0.10723% | 1,072 |
| | | | | Solvent naphtha (petroleum), heavy arom. | PSR-4000 | 64742-94-5 | 0.08460 | 2.50% | 25,000 | 0.05957% | 596 |
| | | | | Copper, [29H,31H-phthalocyaninato(2-)-.kappa.N29,.kappa.N30,.kappa.N31,.kappa.N32]-, (SP-4-1)- | PSR-4000 | 147-14-8 | 0.01861 | 0.55% | 5,500 | 0.01311% | 131 |
| | | | | Naphthalene | PSR-4000 | 91-20-3 | 0.01861 | 0.55% | 5,500 | 0.01311% | 131 |
| | | | | Other components below reportable levels | PSR-4000 | - | 3.02516 | 89.40% | 894,000 | 2.13039% | 21,304 |
| | | | | | | | | 100.00% | 1,000,000 | | |
| | | | | Propanol, 1(or 2)-(2-methoxymethylethoxy)- | CA-40 | 34590-94-8 | 0.25379 | 17.50% | 175,000 | 0.17872% | 1,787 |
| | | | | Epoxy compounds | CA-40 | Trade secret | 0.10877 | 7.50% | 75,000 | 0.07660% | 766 |
| | | | | Other components below reportable levels | CA-40 | - | 1.08767 | 75.00% | 750,000 | 0.76596% | 7,660 |
| | | | | | | | | 100.00% | 1,000,000 | | |
| | | | | Copper | conductive | 7440-50-8 | 17.40697 | 99.98% | 999,800 | 12.25840% | 122,584 |
| | | | | Other ingredients | conductive | - | 0.00348 | 0.02% | 200 | 0.00245% | 25 |
| | | | | 100.00% | 1,000,000 | | | | | | |
| Nickel Metal | wire bond | 7440-02-0 | 0.11161 | 100.00% | 1,000,000 | 0.07860% | 786 | | | | |
| Au | wire bond | 7440-57-5 | 0.01452 | 100.00% | 1,000,000 | 0.01023% | 102 | | | | |
| 3 | Die Attach Material (Tape) | INNOX | IDU0B3L-20T | Epoxy | Adhesive materials for die to die, die to sub UV Cure type | 29690-82-2 | 0.52880 | 20.00% | 200,000 | 0.37239% | 3,724 |
| | | | | Acrylate copolymer | Trade secret | 0.52880 | 20.00% | 200,000 | 0.37239% | 3,724 | |
| | | | | Hardener | Trade secret | 0.26440 | 10.00% | 100,000 | 0.18620% | 1,862 | |
| | | | | Silica | | 7631-86-9 | 1.32200 | 50.00% | 500,000 | 0.93098% | 9,310 |
| | | | | 100.00% | 1,000,000 | | | | | | |
| 4 | Wire | LT Metal | HS-G3 0.7mil | Gold | Balance Material | 7440-57-5 | 0.17131 | 80.05% | 800,500 | 0.12064% | 1,206 |
| | | | | Silver | Enhance mechanical strength | 7440-22-4 | 0.04066 | 19.00% | 190,000 | 0.02863% | 286 |
| | | | | Palladium | Enhance reliability | 7440-05-3 | 0.00201 | 0.94% | 9,400 | 0.00142% | 14 |
| | | | | Others | - | - | 0.00002 | 0.01% | 100 | 0.00002% | 0 |
| | | | | | | | | 100.00% | 1,000,000 | | |
| 5 | Mold Compound | KCC | KTMC5900GPU (16mm x 7.0g) | Silica, vitreous | Filler | 60676-86-0 | 32.72449 | 83.50% | 835,000 | 23.04535% | 230,454 |
| | | | | Silicon dioxide | Filler | 7631-86-9 | 2.15551 | 5.50% | 55,000 | 1.51796% | 15,180 |
| | | | | 4,4'-Bis(2,3-epoxypropoxy)-3,3',5,5'-tetramethyl(1,1'-biphenyl) | Resin | 85954-11-6 | 2.15551 | 5.50% | 55,000 | 1.51796% | 15,180 |
| | | | | Phenol polymer with 1,4-bis(methoxymethyl)benzene | Resin | 26834-02-6 | 1.76360 | 4.50% | 45,000 | 1.24197% | 12,420 |
| | | | | Phenol polymer with formaldehyde | Resin | 9003-35-4 | 0.19596 | 0.50% | 5,000 | 0.13800% | 1,380 |
| | | | | Carbon Black | Colorant | 1333-86-4 | 0.19596 | 0.50% | 5,000 | 0.13800% | 1,380 |
| | | | | 100.00% | 1,000,000 | | | | | | |
| 6 | Solder Ball | Duksan | 0.4mm(Sn/1.2Ag/0.5Cu/0.05Ni) | Tin | Remain | 7440-31-5 | 15.10299 | 98.25% | 982,500 | 10.63588% | 106,359 |
| | | | | Silver | Conductivity Improvement | 7440-22-4 | 0.18446 | 1.20% | 12,000 | 0.12990% | 1,299 |
| | | | | Copper | Heat resistance improvement | 7440-50-8 | 0.07686 | 0.50% | 5,000 | 0.05413% | 541 |
| | | | | Nickel | Thermal stability of alloy | 7440-02-0 | 0.00769 | 0.05% | 500 | 0.00541% | 54 |
| | | | | 100.00% | 1,000,000 | | | | | | |
| Total | | | | | | | 142.00035 | | | 100.00000% | 1,000,000 |